

# 7SB3257

## Mux / Demux Bus Switch

The 7SB3257 Mux / Demux Bus Switch is an advanced high-speed line switch in ultra-small footprint.

### Features

- High Speed:  $t_{PD} = 0.25 \text{ ns (Max) @ } V_{CC} = 4.5 \text{ V}$
- $3 \Omega$  Switch Connection Between 2 Ports
- Power Down Protection Provided on Inputs
- Ultra-Small Packages
- These are Pb-Free Devices

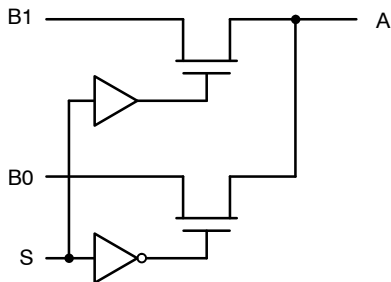


Figure 1. Logic Diagram

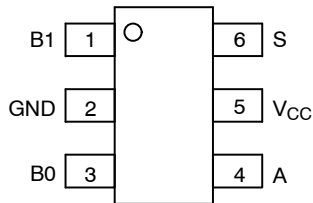


Figure 2. TSOP-6/SC-88 (Top View)

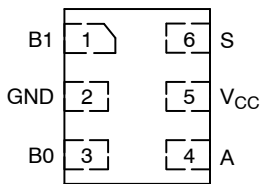


Figure 3. ULLGA6/UDFN6 (Top View)

### Function Table

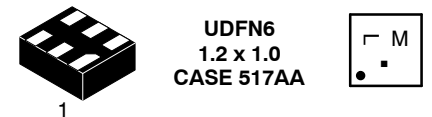
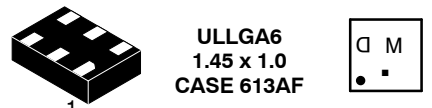
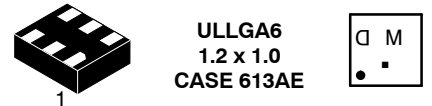
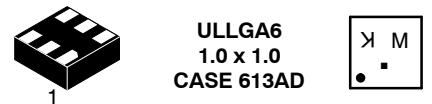
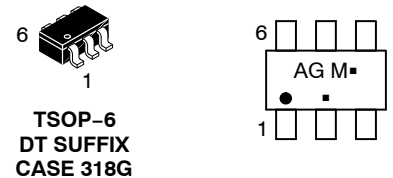
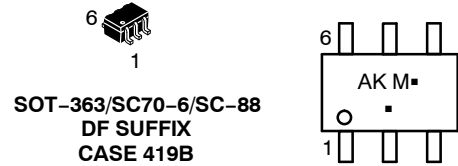
Input S	Function
L	A = B0
H	A = B1



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### MARKING DIAGRAMS



AK, AG, K, D, L = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Table 1. MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage	-0.5 to +7.0	V
$V_{IN}$	Control Pin Input Voltage	-0.5 to +7.0	V
$V_{I/O}$	Switch Input / Output Voltage	-0.5 to +7.0	V
$I_{IK}$	Control Pin DC Input Diode Current	$V_{IN} < GND$ -50	mA
$I_{OK}$	Switch I/O Port DC Diode Current	$V_{I/O} < GND$ -50	mA
$I_O$	On-State Switch Current	±128	mA
	Continuous Current Through $V_{CC}$ or GND	±150	mA
$I_{CC}$	DC Supply Current per Supply Pin	±150	mA
$I_{GND}$	DC Ground Current per Ground Pin	±150	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	°C
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
$T_J$	Junction Temperature Under Bias	150	°C
$\theta_{JA}$	Thermal Resistance	SC-88 / TSOP-6 (Note 1) ULLGA6/UDFN6 333 496	°C/W
$P_D$	Power Dissipation in Still Air at 85°C	SC-88 / TSOP-6 (Note 1) ULLGA6/UDFN6 200 252	mW
MSL	Moisture Sensitivity	Level 1	
$F_R$	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
$V_{ESD}$	ESD Withstand Voltage	Human Body Mode (Note 2) Machine Mode (Note 3) Charged Device Mode (Note 4) >2000 >200 N/A	V
$I_{LATCHUP}$	Latchup Performance Above $V_{CC}$ and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/ JESD22-A114-A
3. Tested to EIA/ JESD22-A115-A
4. Tested to JESD22-C101-A
5. Tested to EIA / JESD78.

Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Positive DC Supply Voltage	4.0	5.5	V
$V_I$	Control Pin Input Voltage	0	5.5	V
$V_{I/O}$	Switch Input / Output Voltage	0	5.5	V
$T_A$	Operating Free-Air Temperature	-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	Control Input Switch I/O 0 0	5 DC	nS/V

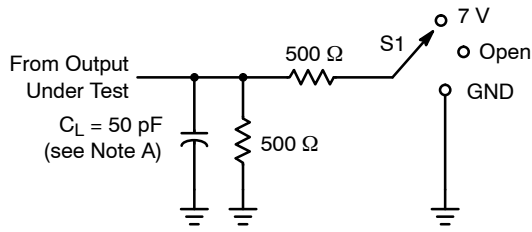
Table 3. DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> = -18 mA	4.5			-1.2		-1.2	V
V <sub>IH</sub>	High-Level Input Voltage (Control)		4.0 to 5.5	2.0			2.0		V
V <sub>IL</sub>	Low-Level Input Voltage (Control)		4.0 to 5.5			0.8		0.8	V
I <sub>IN</sub>	Input Leakage Current	0 ≤ V <sub>IN</sub> ≤ 5.5 V	5.5			±0.1		±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>I/O</sub> = 0 to 5.5 V	0			±0.1		±1.0	μA
I <sub>CC</sub>	Quiescent Supply Current	I <sub>O</sub> = 0, V <sub>IN</sub> = V <sub>CC</sub> or 0 V	5.5			±0.1		±1.0	μA
ΔI <sub>CC</sub>	Increase in Supply Current (Control Pin)	One input at 3.4 V; Other inputs at V <sub>CC</sub> or GND	5.5					2.5	mA
R <sub>ON</sub>	Switch ON Resistance	V <sub>I/O</sub> = 0, I <sub>I/O</sub> = 64 mA I <sub>I/O</sub> = 30 mA	4.5		3 3	7 7		7 7	Ω
		V <sub>I/O</sub> = 2.4, I <sub>I/O</sub> = 15 mA	4.5		6	15		15	
		V <sub>I/O</sub> = 2.4, I <sub>I/O</sub> = 15 mA	4.0		10	20		20	

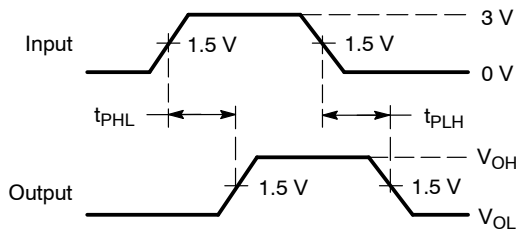
Table 4. AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	Test Condition	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t <sub>PD</sub>	Propagation Delay, A to B or B to A	4.0 to 5.5	See Figure 4			0.25		0.25	ns
t <sub>EN</sub>	Output Enable Time	4.5 to 5.5		0.8	2.5	4.2	0.8	4.2	
		4.0		0.8	3.0	4.6	0.8	4.6	
t <sub>DIS</sub>	Output Disable Time	4.5 to 5.5		0.8	3.1	4.8	0.8	4.8	ns
		4.0		0.8	2.9	4.4	0.8	4.4	
C <sub>IN</sub>	Control Input Capacitance	5.0		V <sub>IN</sub> = 3 V or 0		2.0			pF
C <sub>IO(ON)</sub>	Switch On Capacitance	5.0	Switch ON		10			pF	
C <sub>IO(OFF)</sub>	Switch Off Capacitance	5.0	Switch OFF		3.5			pF	

AC Loading and Waveforms

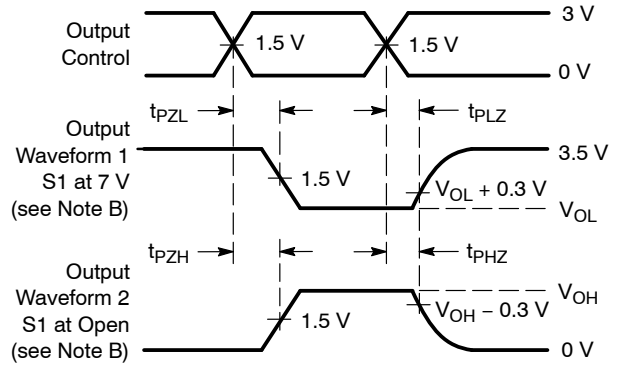


LOAD CIRCUIT



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES

TEST	S1
$t_{PD}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	GND



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
- D. The output is measured with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 4. Load Circuit and Voltage Waveforms

DEVICE ORDERING INFORMATION

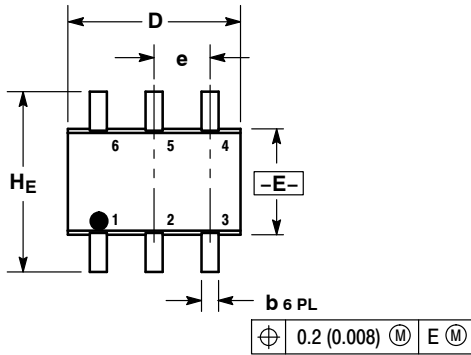
Device	Package	Shipping <sup>†</sup>
7SB3257DTT1G	TSOP-6 (Pb-Free)	3000 / Tape & Reel
7SB3257DFT2G	SC-88 (Pb-Free)	3000 / Tape & Reel
7SB3257AMX1TCG	ULLGA6 – 0.5 mm Pitch (Pb-Free)	3000 / Tape & Reel
7SB3257BMX1TCG	ULLGA6 – 0.4 mm Pitch (Pb-Free)	3000 / Tape & Reel
7SB3257CMX1TCG	ULLGA6 – 0.35 mm Pitch (Pb-Free)	3000 / Tape & Reel
7SB3257MUTCG	UDFN6 – 0.4 mm Pitch (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# 7SB3257

## PACKAGE DIMENSIONS

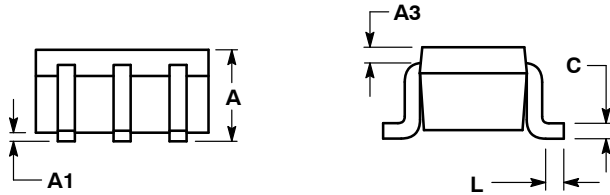
SC-88/SC70-6/SOT-363  
CASE 419B-02  
ISSUE W



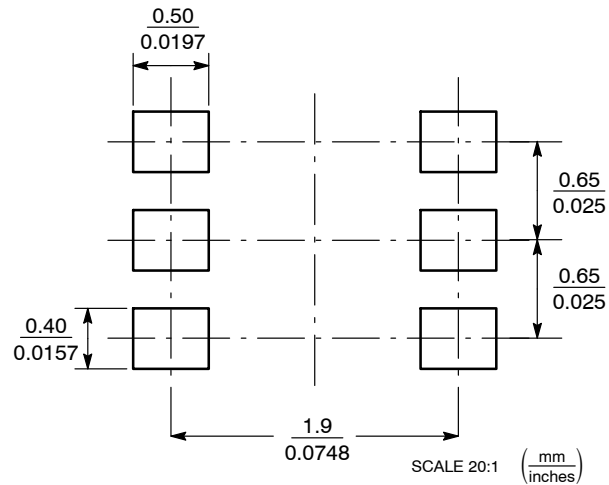
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.20 REF			0.008 REF		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	2.00	2.10	2.20	0.078	0.082	0.086



### SOLDERING FOOTPRINT\*

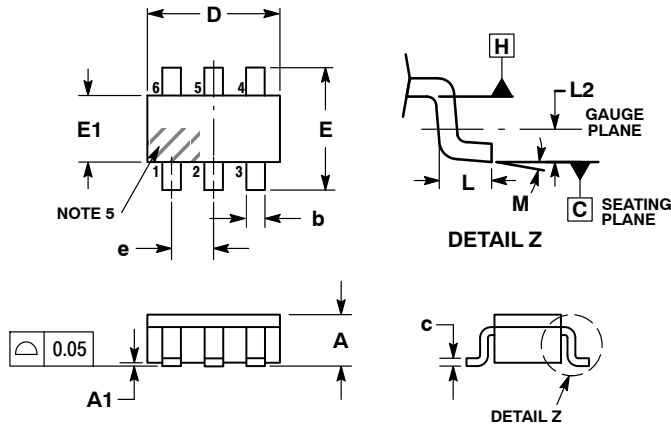


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# 7SB3257

## PACKAGE DIMENSIONS

TSOP-6  
CASE 318G-02  
ISSUE U

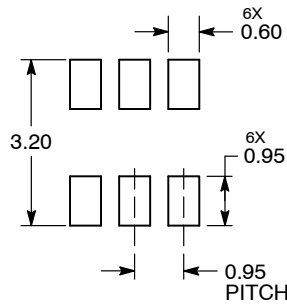


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	-	10°

### RECOMMENDED SOLDERING FOOTPRINT\*



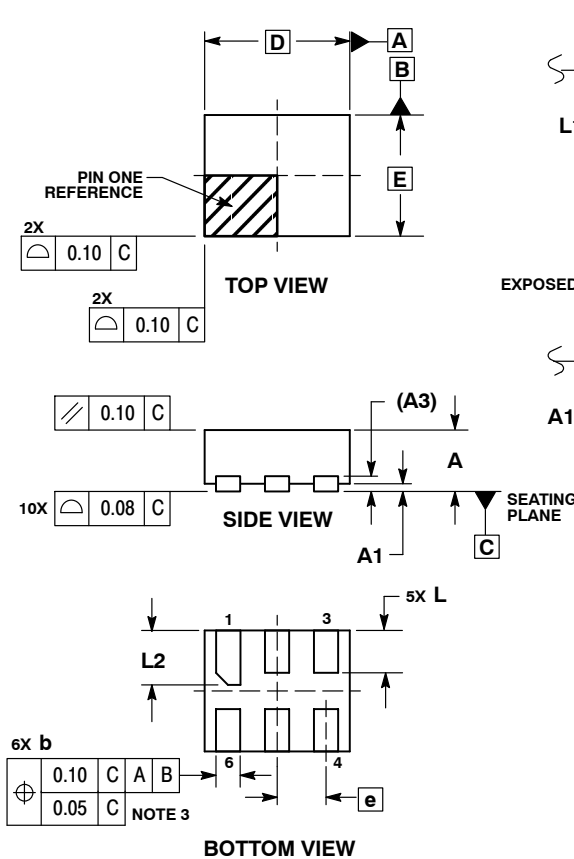
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# 7SB3257

## PACKAGE DIMENSIONS

UDFN6 1.2x1.0, 0.4P  
CASE 517AA-01  
ISSUE C

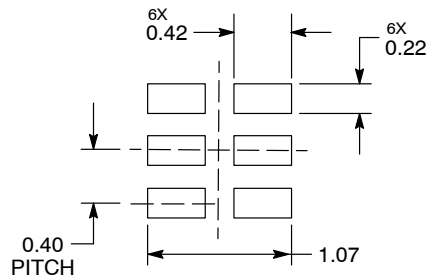


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127	REF
b	0.15	0.25
D	1.20	BSC
E	1.00	BSC
e	0.40	BSC
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50

**MOUNTING FOOTPRINT\***



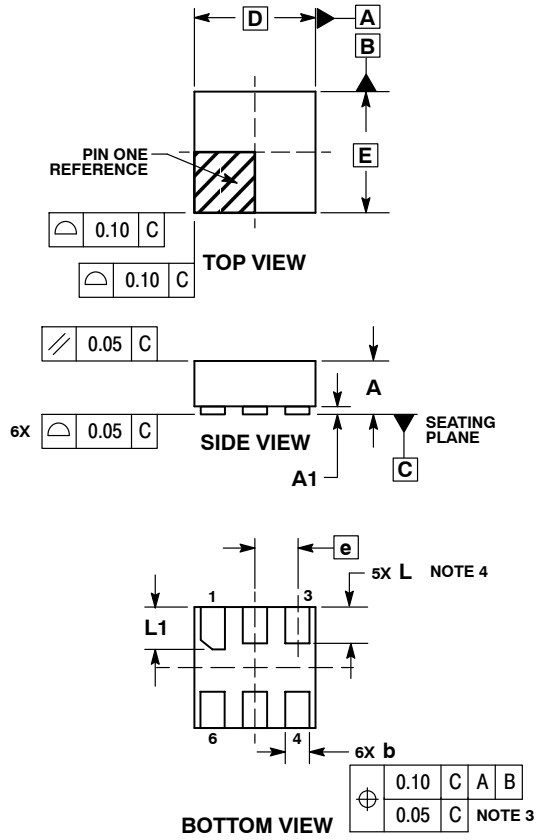
DIMENSIONS: MILLIMETERS

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# 7SB3257

## PACKAGE DIMENSIONS

### ULLGA6 1.0x1.0, 0.35P CASE 613AD-01 ISSUE A

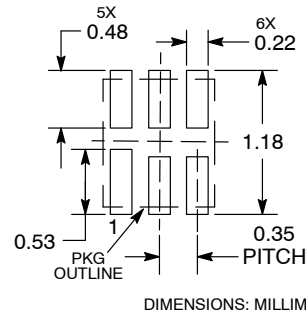


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



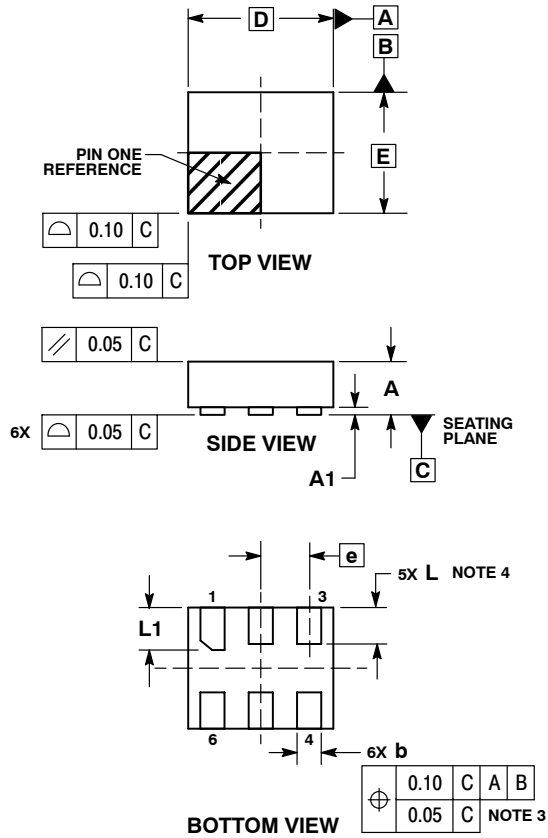
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



# 7SB3257

## PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P  
CASE 613AE-01  
ISSUE A

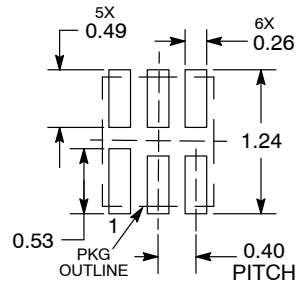


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

**MOUNTING FOOTPRINT  
SOLDERMASK DEFINED\***



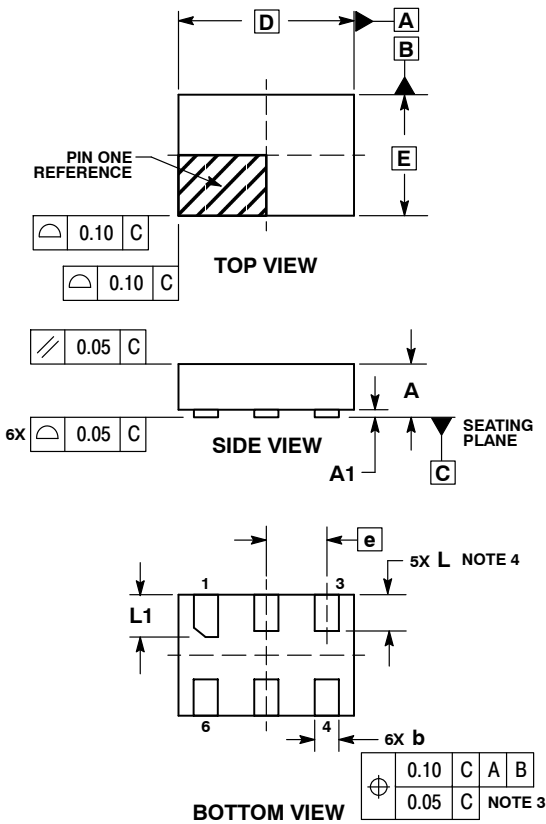
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# 7SB3257

## PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P  
CASE 613AF-01  
ISSUE A

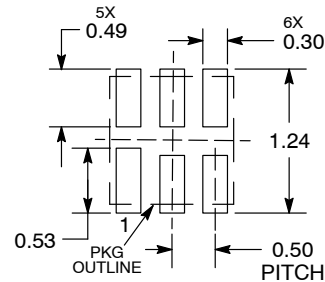


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
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4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

### MOUNTING FOOTPRINT SOLDERMASK DEFINED\*



DIMENSIONS: MILLIMETERS

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- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.

